

Page 12, Line 3, change "die" to --dice--.

Page 12, Line 4, change "die" to --dice--.

Page 12, Line 11, change "die 14" to --dice 14A and 14B--.

Page 12, Line 14, change "are" to --is--.

Page 12, Line 22, change "die" to --dice--.

Page 12, Line 23, change "die" to --dice--. (which occurrence)

Page 12, Line 26, change "die" (1st occur.) to --dice--.

Page 12, Line 26, change "die" (2nd occur.) to --dice--.

NE Page 12, Line 26, change "die" (3rd occur.) to --dice--.

IN THE ABSTRACT:

Please amend the abstract as follows:

Page 19, Line 5, change "with" (1st occur.) to --to--.

Page 19, Line 13, change "die" (1st occur.) to --dice--.

Page 19, Line 13, change "die" (2nd occur.) to --dice--.

Page 19, Line 14, change "die" to --dice--.

IN THE DRAWINGS:

A corrected FIG. 5 with changes in red ink and a replacement informal drawing for FIG. 5 are provided for the Examiner's approval. Element 30A was inadvertently labeled as 30B. This mislabeling has been corrected. The indications of elements 52 and 56, as disclosed on page 12, lines 11 and 13, respectively, which were inadvertently omitted, have been added.

IN THE CLAIMS:

Please amend the claims 19, 21-23, 26-30, 33, and 34, as follows:

19. (Amended) A method of fabricating a multi-die assembly, comprising:
providing a substrate including a plurality of conductors;

a'
sub circuit